

# ABIT- 陞技電腦股份有限公司

## Thermal Test Report

Project No. :

Apply Date :

### Test Report

PM :	Grand	Test Date :	2001/3/11
Test Sample :	Pentium4 Xeon	Parts List :	
Test software : Maxpower version6 + EMI test program			
Test Content			
A、 Test Purpose and Method			
1. Test Purpose : Thermal performance predict.			
2. Test Method : Running Maxpower version 6 @ 100% loading			
3. Test Model : SI-2P			
B、 Test Equipment :			
Thermal Recorder : YOKOGAWA DA-230			
C、 Test Item and Condition :			
Environmental : Temp : 35 °C ; Humidity : 80 %RH ; Time : 72 HR			
D、 Test Result :	GOOD	FAIL	REF
E、 Proposal/Statement :			
Approved By :		Prepared By :	Issue Date : 0311/2002

## ***Test Configuration***

<b>Component Description</b>	<b>Test Configuration</b>
Motherboard	Ok
CPU	Ok
DIMM	Ok
Hard Drive	Ok
CD-ROM	Ok
Floppy Drive	Ok
Power Supply	Ok
CPU Cooler	Ok
System fan	Ok

## ***Test Setup and procedure***

### ***Test methodology:***

1. The thermocouple 1 stick on CPU 1
2. The thermocouple 2 stick on CPU 2
3. The thermocouple 3 stick on Troom
4. The thermocouple 4 stick on SB
5. The thermocouple 5 stick on NB
6. The thermocouple 6 stick on HDD
7. The thermocouple 7 stick on MOSFE
8. The thermocouple 8 stick on RAM
9. The thermocouple 9 stick on POWER

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## **7. Test Program and Environmental requirement**

1. Running programs : Maxpower version 6 + EMI test program
2. Ambient Temperature : 35
3. Ambient humidity : 80%

## **8. Test Results**

Test Point	SPEC	Temperature
Tcase of CPU 1	68	52.0
Tcase of CPU 2	68	52.5
Troom	45	40.6
South Bridge	110	56.3
North Bridge	100	73.5
HDD	55	40.8
RAM	90	51.4
MOSFE	130	58.7
POWER	50	47.8